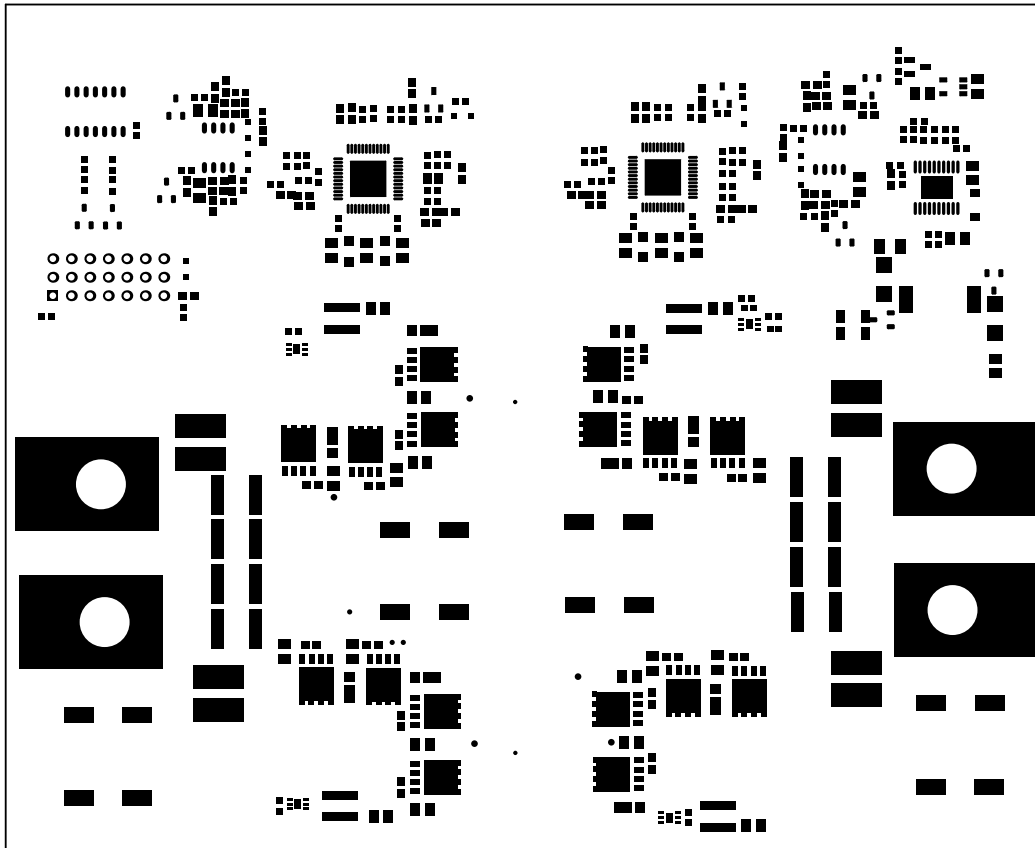
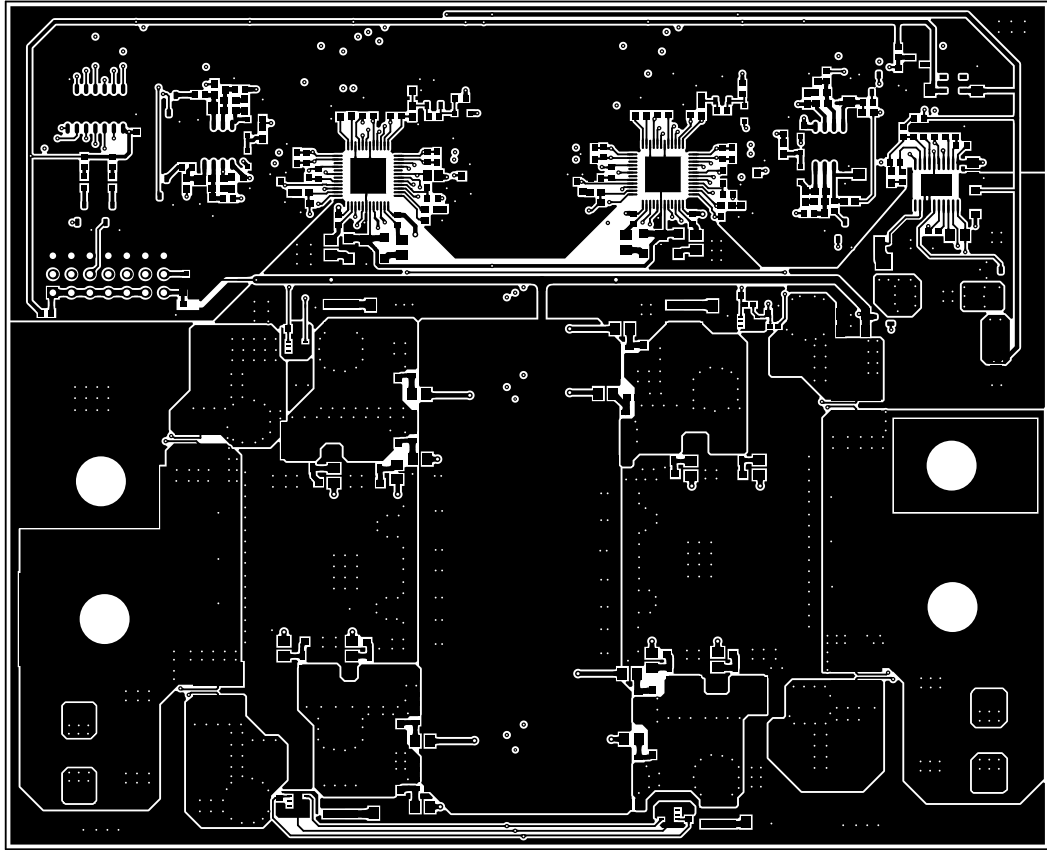


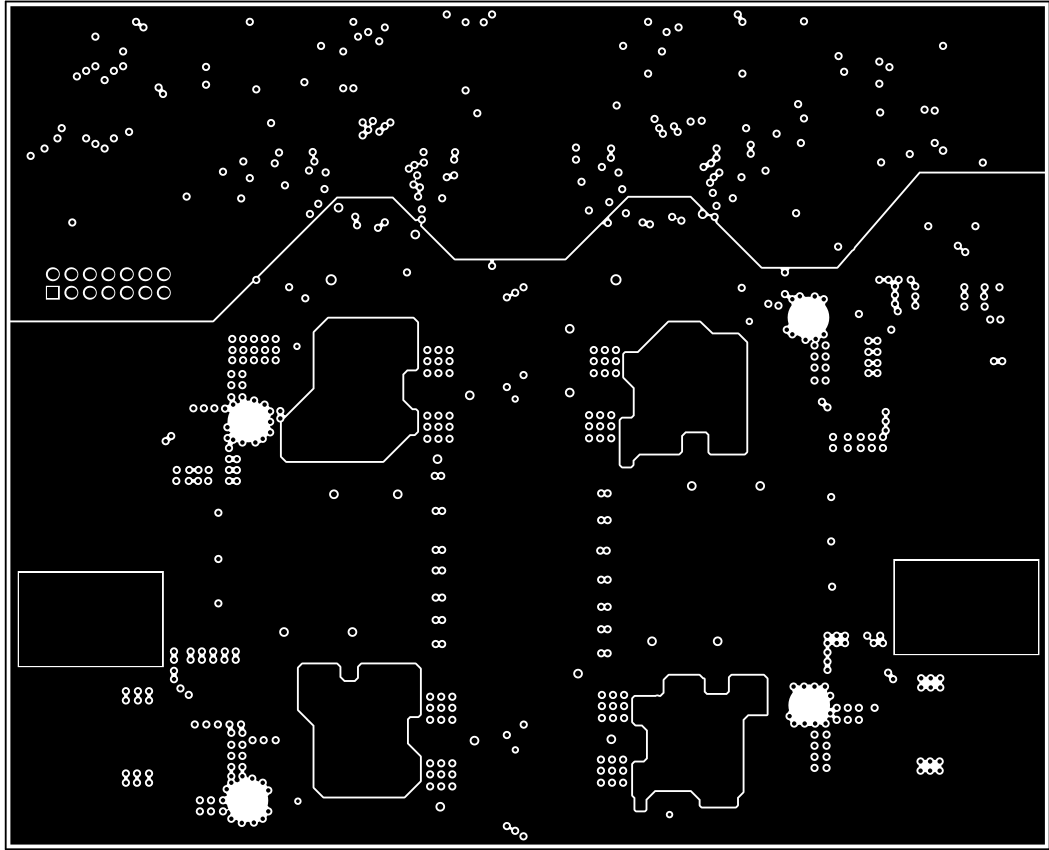
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 6/14/2018	5:48:38 PM	TEXAS INSTRUMENTS



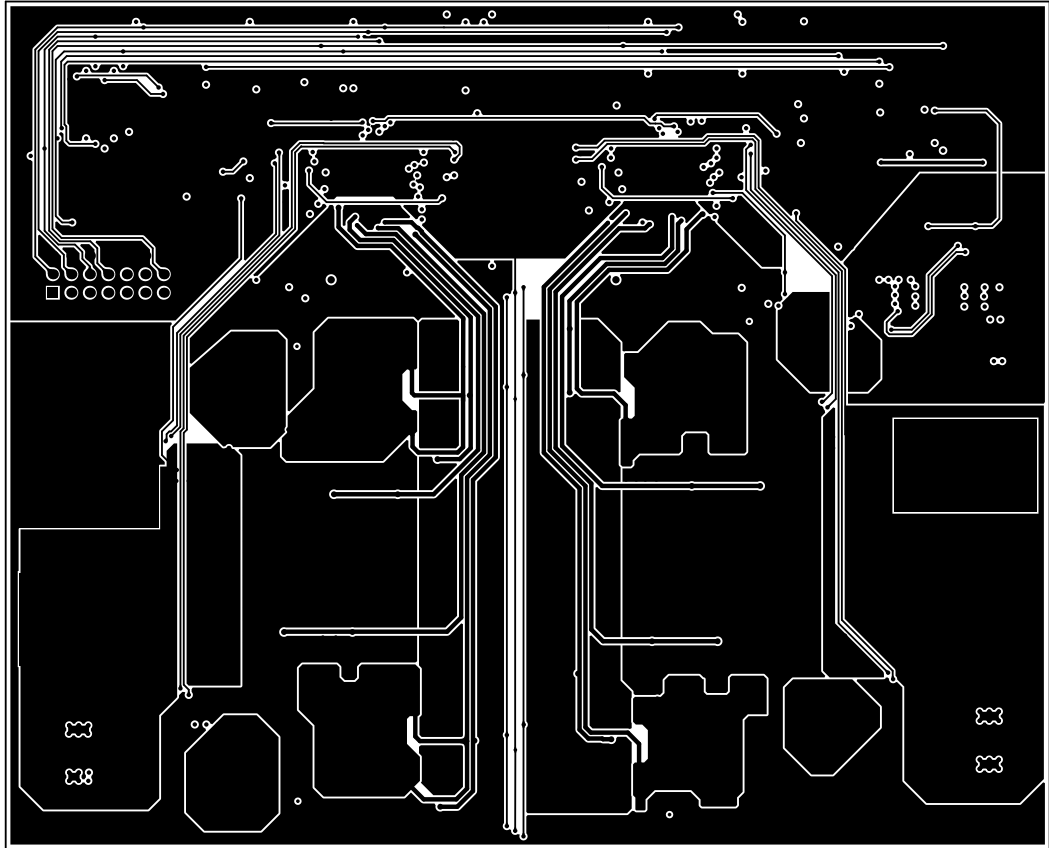
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 6/14/2018	5:48:40 PM	TEXAS INSTRUMENTS



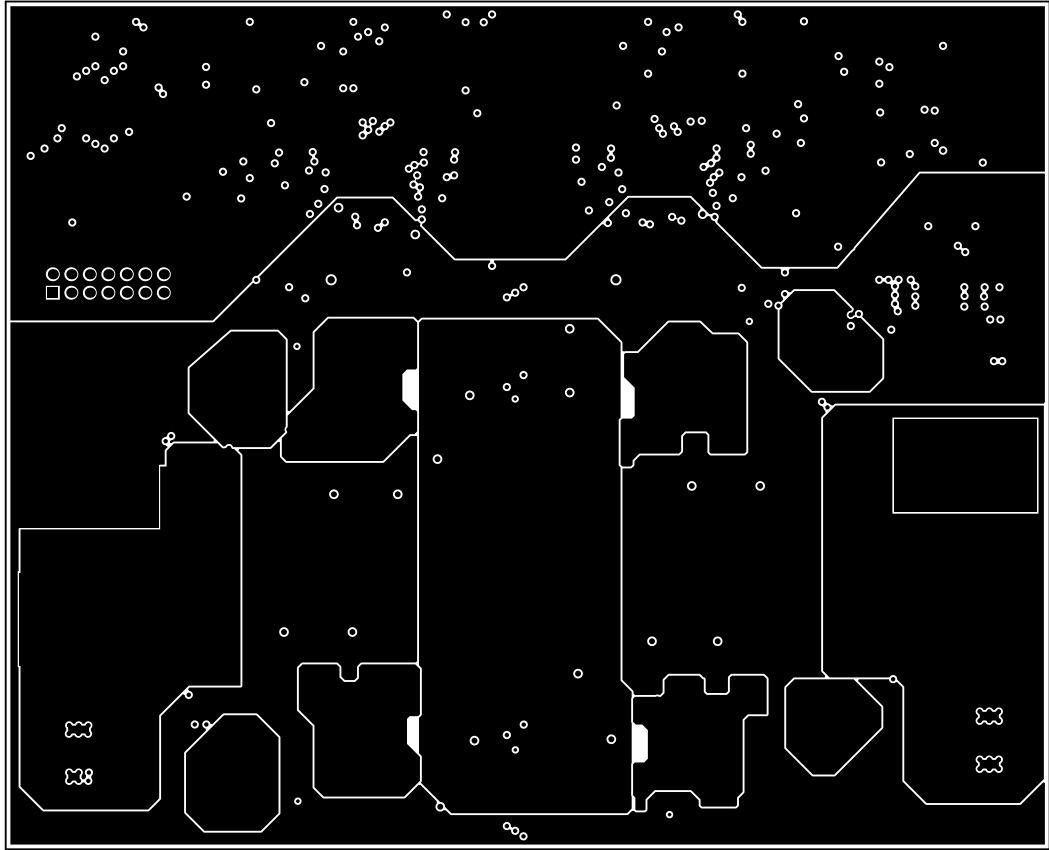
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP15035	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Layer	TID #:	N/A			
PLOT NAME =	Top Layer	GENERATED :	6/14/2018	5:48:42 PM	TEXAS INSTRUMENTS	



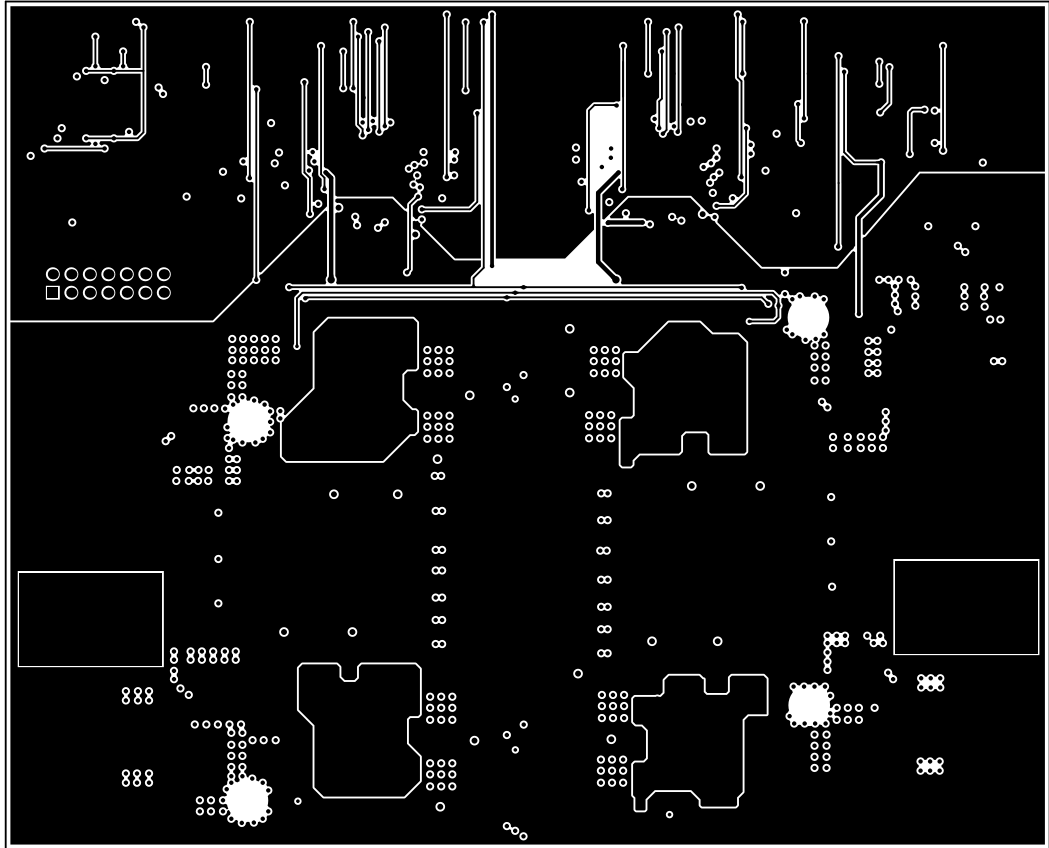
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: N/A		
PLOT NAME = Signal 1	GENERATED : 6/14/2018 5:48:43 PM	TEXAS INSTRUMENTS	



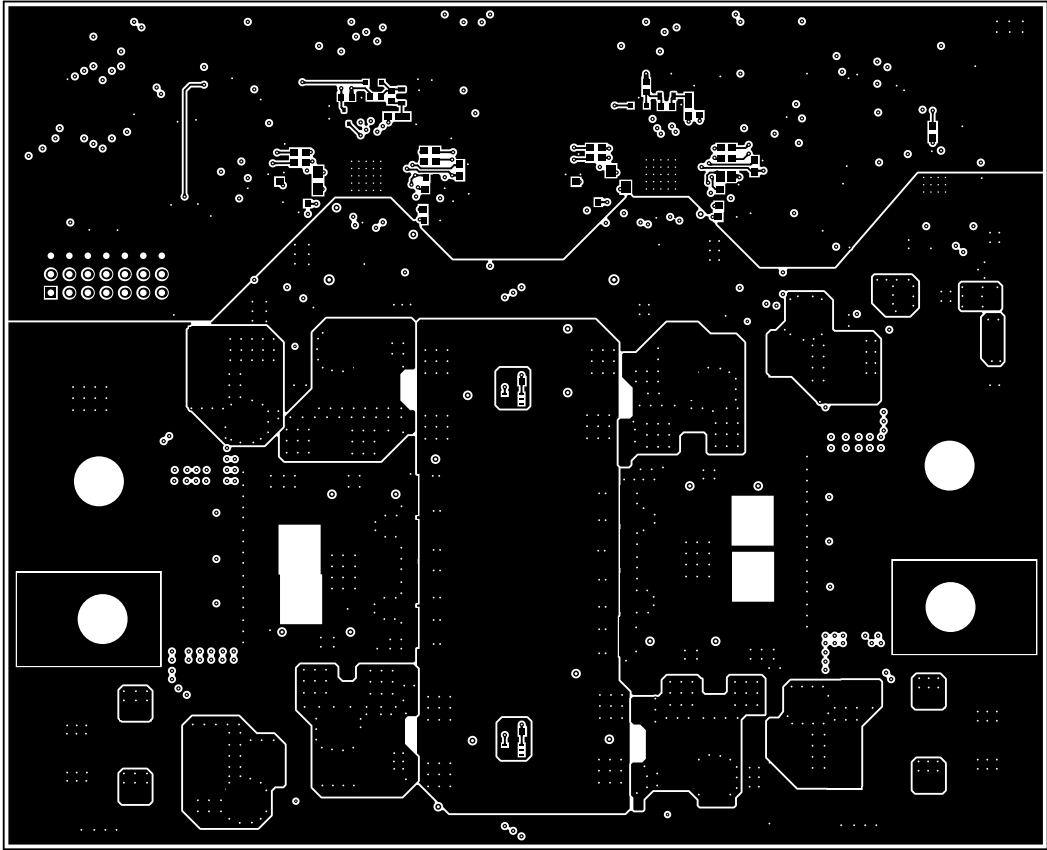
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: N/A		
PLOT NAME = Signal 2	GENERATED : 6/14/2018 5:48:44 PM	TEXAS INSTRUMENTS	



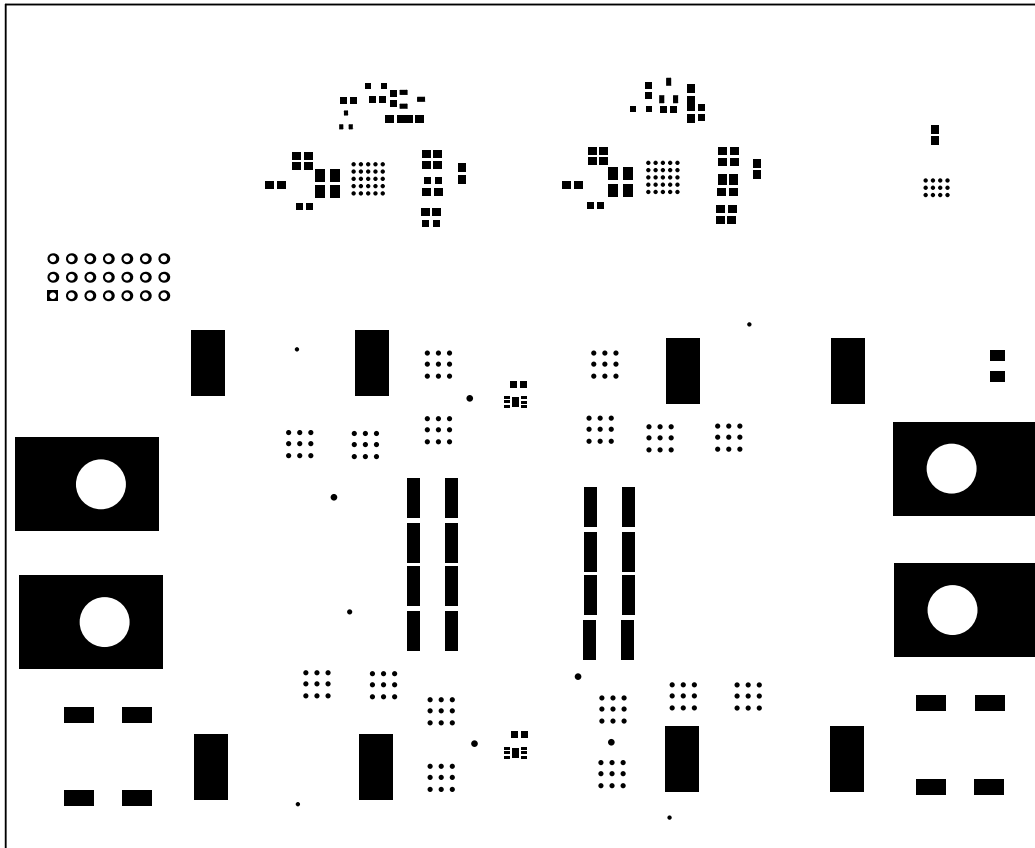
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 3	TID #: N/A		
PLOT NAME = Signal 3	GENERATED : 6/14/2018 5:48:45 PM	TEXAS INSTRUMENTS	



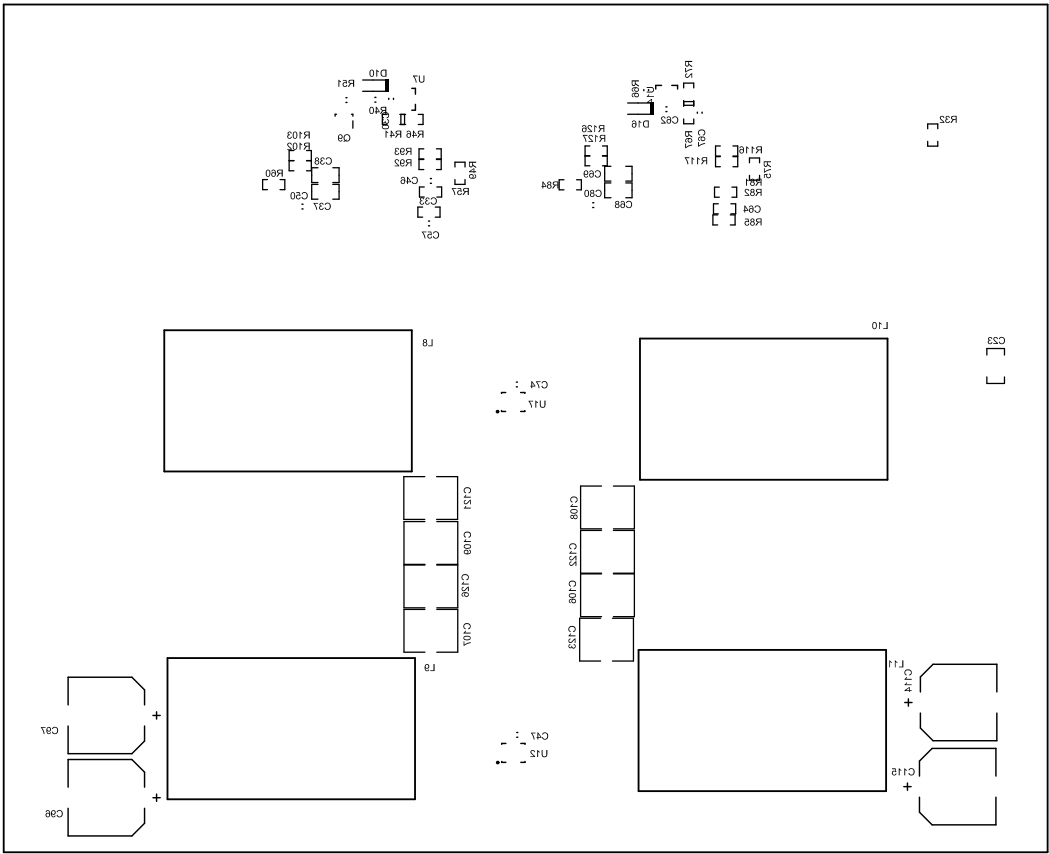
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 4	TID #: N/A		
PLOT NAME = Signal 4	GENERATED : 6/14/2018 5:48:46 PM	TEXAS INSTRUMENTS	



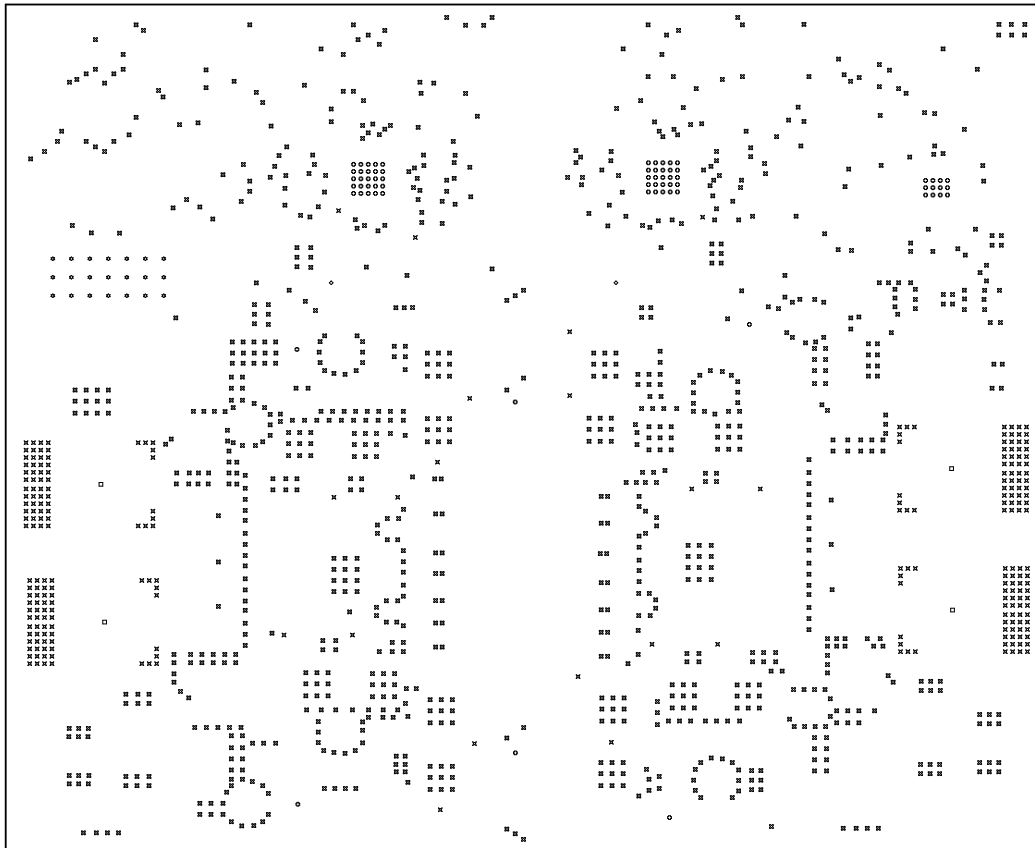
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 6/14/2018	5:48:48 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/14/2018 5:48:49 PM	TEXAS INSTRUMENTS	

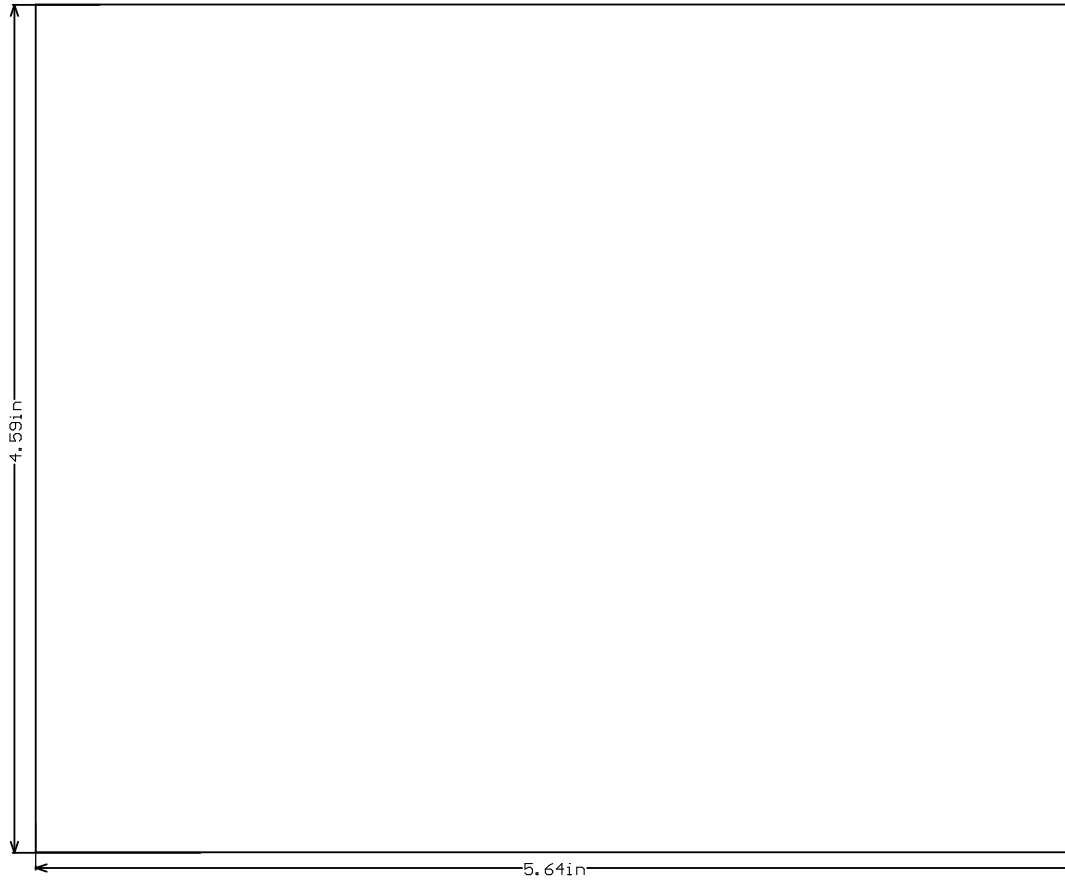


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 6/14/2018	5:48:50 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊙	68	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	1028	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	251	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
◇	2	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
☆	21	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	270.00mil (6.858mm)	PTH	Round	Top Layer - Bottom Layer	
1374 Total						

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP15035	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Drill Drawing	TID #:	N/A			
PLOT NAME =	Drill Drawing	GENERATED :	6/14/2018	5:48:51 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15035	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = H2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 6/14/2018	5:48:56 PM	TEXAS INSTRUMENTS

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